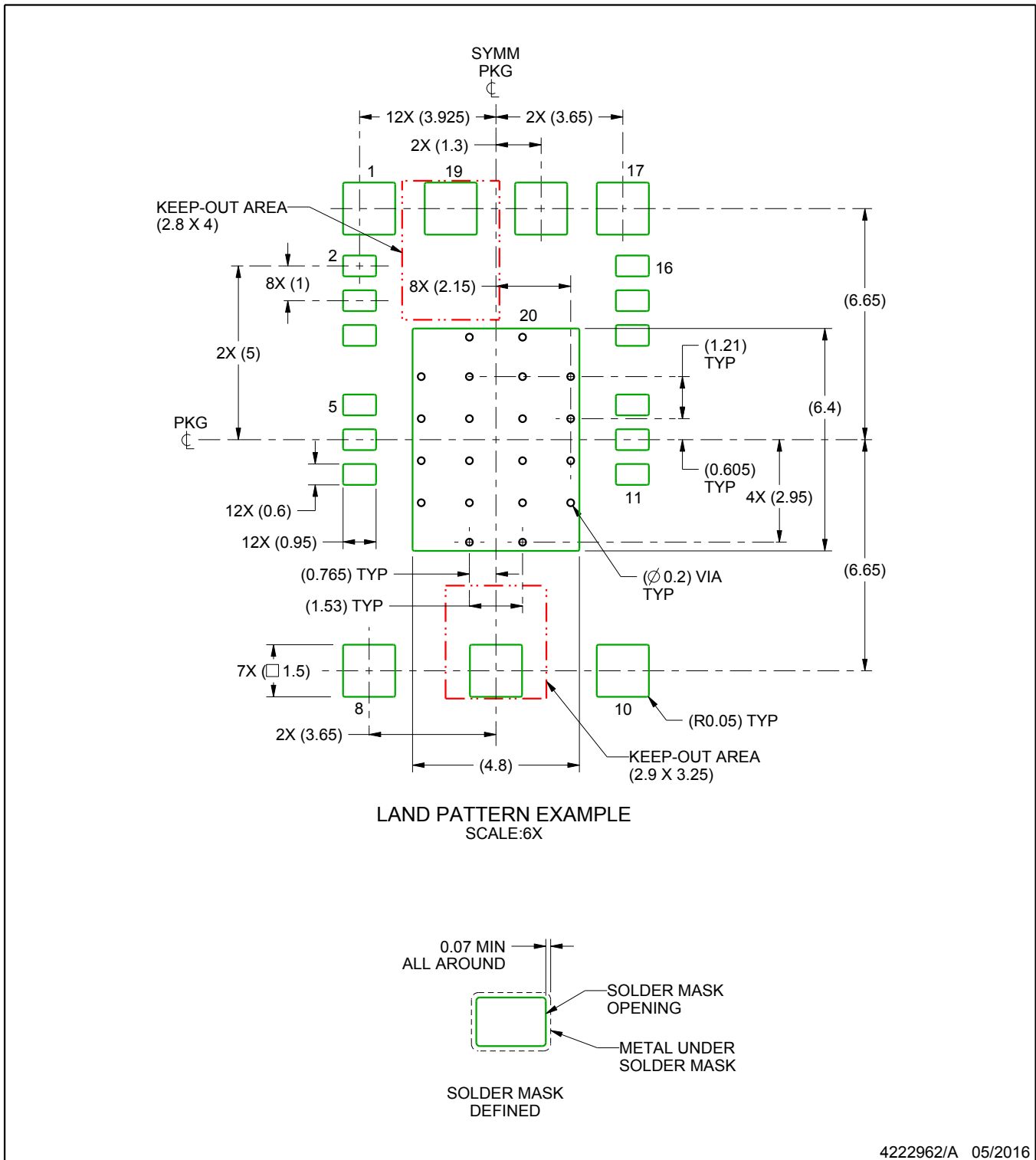


EXAMPLE BOARD LAYOUT

MOJ0020A

QFM - 2.3 mm max height

QUAD FLAT MODULE



NOTES: (continued)

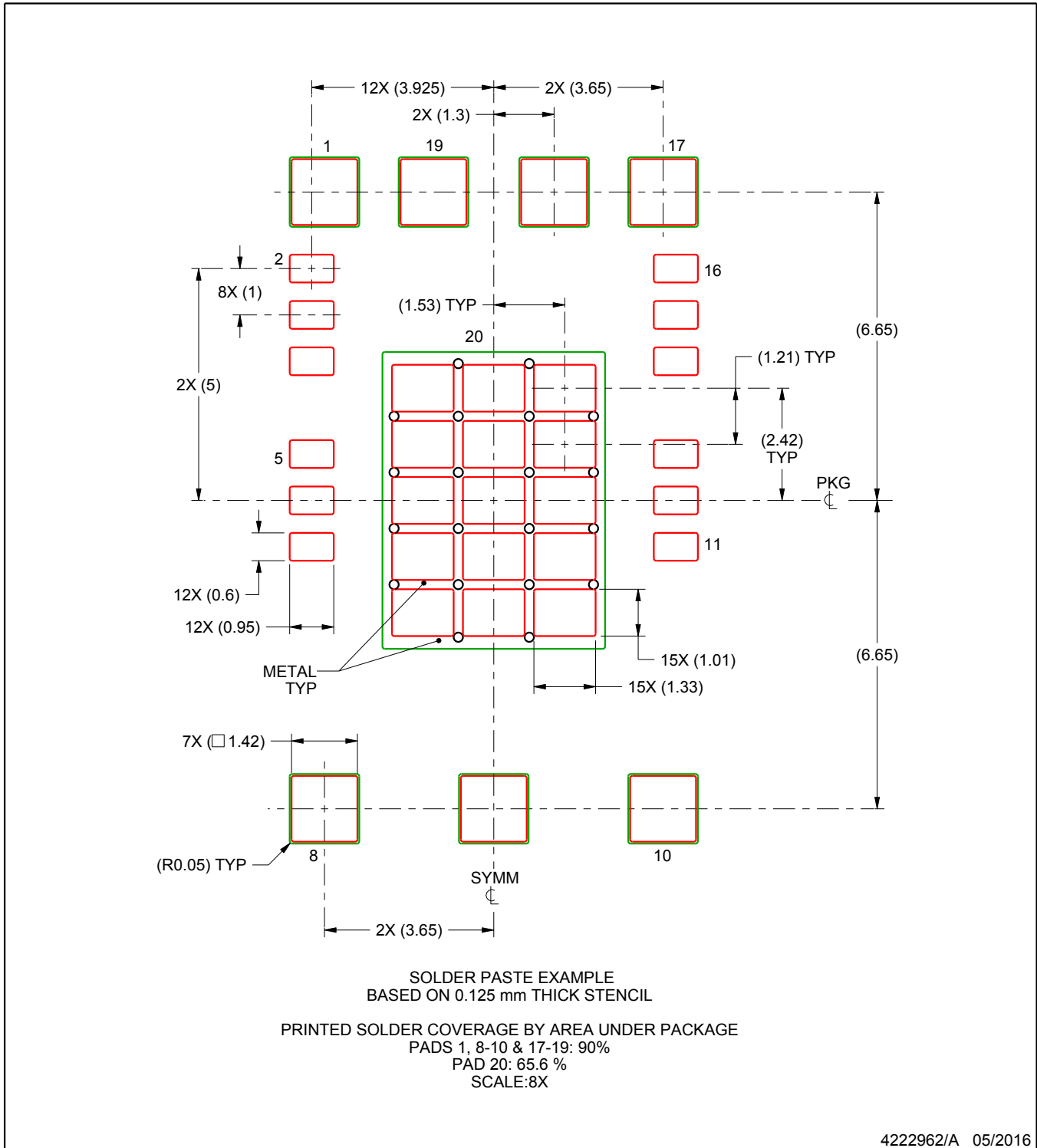
- This package is designed to be soldered to thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sl原因271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view.

EXAMPLE STENCIL DESIGN

MOJ0020A

QFM - 2.3 mm max height

QUAD FLAT MODULE



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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